

ELECTRONIC COMPONENT PACKAGING SHEET, AND FORMED ARTICLE THEREOF

ABSTRACT

Disclosed is an electronic component packaging sheet comprising a surface conductive layer formed on the surface of at least one side of a substrate sheet. The substrate sheet comprises (A) 80,000 to 220,000 Mw of a styrene-conjugated diene block copolymer; (B) 200,000 to 400,000 Mw of a polystyrene resin; and (C) 150,000 to 210,000 Mw of an impact resistant polystyrene resin. The surface conductive layer comprises (D) an acrylic copolymer resin; and (E) a polythiophene type polymer, particularly a polythiophene type polymer/anionic polymer ion complex. The electronic component packaging sheet is a transparent conductive sheet having excellent thermoforming properties, good transparency after thermoforming, and sufficient electrostatic diffusion performance to maintain a low surface resistance value. The electronic component packaging sheet is particularly suited for the manufacture of embossed carrier tape.

No suitable figure